

ABSTRACT OF THE DISCLOSURE

A filter device includes a filter element that has piezoelectric thin-film resonators arranged in series arms and parallel arms, and a package that
5 houses the filter element in a face-down state. In this filter device, the filter element and the package are electrically connected to each other through bumps. The package includes first pad parts on which the bumps are placed, and transmission paths that electrically
10 connect the first pad parts to the outside. The filter element includes second pad parts that are electrically connected to the first pad parts through the bumps, and wiring parts that electrically connect the second pads to the piezoelectric thin-film resonators and
15 electrically connect the piezoelectric thin-film resonators to one another. In this structure, inductances formed with the transmission paths are connected in series to the piezoelectric thin-film resonators.
20